

DATA SHEET

● DEVICE NUMBER: BL-HB536A-AV-TRB

SHEET	1	2	3	4	5	6	7		CONTENTS
2005.06.22	1.0	1.0	1.0	1.0	1.0	1.0	1.0		Original Released
2009.05.26	1.1	1.1	1.1	1.1	1.1	1.1	1.1		ChangeTest Condition
2010.03.26	1.2	1.2	1.2	1.2	1.2	1.2	1.2		Modify 3K/reel to 4K/reel
2012.07.05					1.3				Updated reliability testing

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BL-HB536A-AV-TRB

Features:

1. Emitted Color: Super Blue

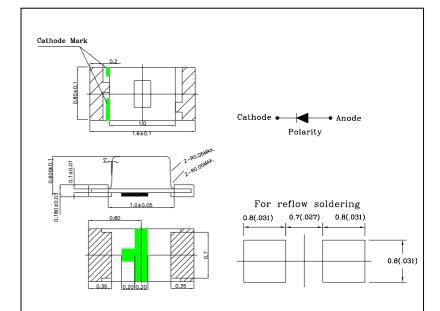
2. Lens Appearance: Water Clear

- 3. Mono-color type.
- 4. 1.6x0.8x0.6mm(0603) standard package
- 5. Suitable for all SMT assembly methods.
- Compatible with infrared and vapor phase reflow solder process.
- Compatible with automatic placement equipment.
- This product doesn't contain restriction Substance, comply ROHS standard.

Applications:

- Automotive : Dashboards, stop lamps, turn signals.
- 2. Backlighting: LCDs, Key pads advertising.
- 3. Status indicators : Comsumer & industrial electronics.
- 4. General use.

Package Dimensions:



NOTES:

- 1.All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.10mm (0.004") unless otherwise specified.
- 3. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	72	mW
Forward Current	l _F	20	mA
Peak Forward Current *1	I _{FP}	100	mA
Reverse Volage	V _R	5	V
Operating Temperature	Topr	-40℃~85℃	-
Storage Temperature	Tstg	-40℃~85℃	-
Soldering Temperature	Tsol	See Page6	-

 $[\]ensuremath{ \star 1}$ Condition for IFp is pulse of 1/10 duty and 0.1msec width.

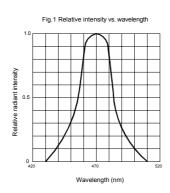


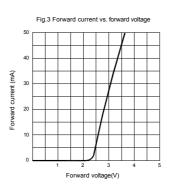
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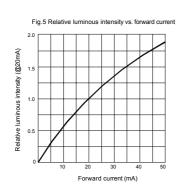
■ Electrical and optical characteristics(Ta=25°C)

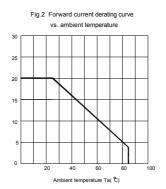
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf	IF=20mA	-	3.2	3.6	V
Luminous Intensity	lv	IF=20mA	42	80	-	mcd
Reverse Current	I_R	V _R =5V	-	-	100	μΑ
Peak Wave Length	λр	IF=20mA	-	470	-	nm
Dominant Wave Length	λ d	IF=20mA	465	-	470	nm
Spectral Line Half-width	Δλ	IF=20mA	-	30	-	nm
Veiwing Angle	2θ _{1/2}	IF=20mA	-	120	-	deg

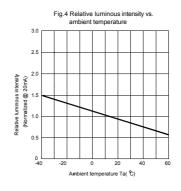
■ Typical Electro-Optical Characteristics Curves

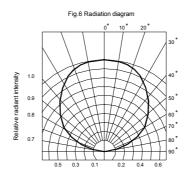








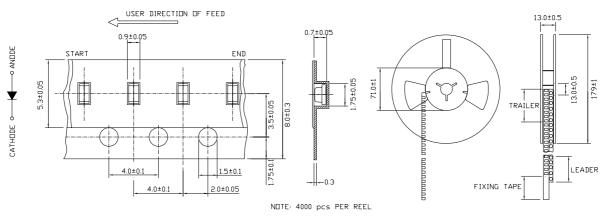




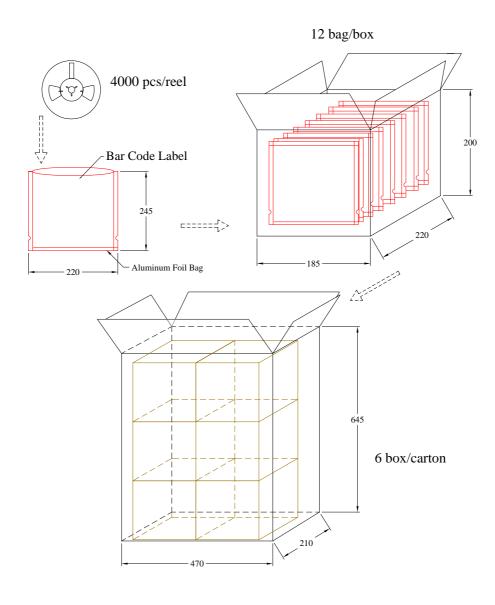


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● Tapping and packaging specifications(Units: mm) Quantity:1000-4000PCS



● Package Method: (unit:mm) Vacuum





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Bin Limits

Intensity Bin Limits (At 20mA)

BIN CODE	Min. (mcd)	Max. (mcd)		
N	42	63		
Р	63	94		
Q	94	140		
R	140	210		

Tolerance for each Bin limit is \pm 15%.

Color Bin Limits (At 20mA)

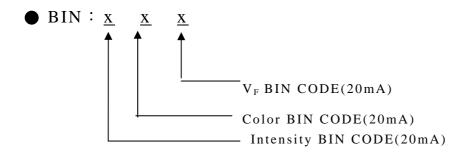
BIN CODE	Min. (nm)	Max. (nm)	
4	465	470	

Tolerance for each Bin limit is ± 1nm

V_F Bin Limits (At 20mA)

BIN CODE	Min.(v)	Max.(v)		
G	2.8	3.0		
Н	3.0	3.2		
J	3.2	3.4		
K	3.4	3.6		

Tolerance for each Bin limit is ± 0.05V.





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Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
	Operation Life	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS-C-7021 :B-1	Ta: Under room temperature Test time:1,000hrs IF=Product Recommended IF	0/32
Endurance	High Temperature High Humidity Storage	MIL-STD-202F:103B JIS-C-7021 :B-11	Ta:85±5℃ RH:90%-95% Test time:240hrs	0/32
Test	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	Ta:100±5℃ Test time:1,000hrs	0/32
	Low Temperature Storage	JIS-C-7021 :B-11	Ta: -40±5℃ Test time=1,000hrs	0/32
	Temperature Cycling	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS-C-7021 :A-2	Ta:- $35\pm5^{\circ}$ C ~ $25\pm5^{\circ}$ C ~ $85\pm5^{\circ}$ C ~ $25\pm5^{\circ}$ C 30min 5min 5min	0/32
Environmental Test	Thermal Shock	MIL-STD-202F:107D(1980) MIL-STD-750D:1051(95) MIL-STD-883D:1011(1 991)	Ta:-40±5°C ~+85±5°C 10min 10 min Time: 20min/cycle 10cycle	0/32
Wetting		MIL-STD-883:2003 MIL-STD-202F:208D MIL-STD-883D:2003	Ta:230±5°ℂ Time:5±0.5s	0/32

Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgement criteria for failure	
Forward voltage	$V_{F}(V)$	I _F =20mA	Initial Level*1.1	
Reverse current	I _R (uA)	V _R =5V	Over U*2	
Luminous intensity	lv (mcd)	I _F =20mA	Initial Level*0.7	

Note: 1.U means the upper limit of specified characteristics.

2. Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.



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Soldering :

1. Manual of Soldering

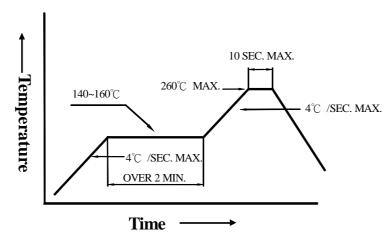
The temperature of the iron tip should not be higher than 300° C (572°F) and Soldering within 3 seconds per solder-land is to be observed.

2. Reflow Soldering

Preheating: 140°C ~160°C ±5°C, within 2 minutes.

Operation heating: 260°C (Max.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).

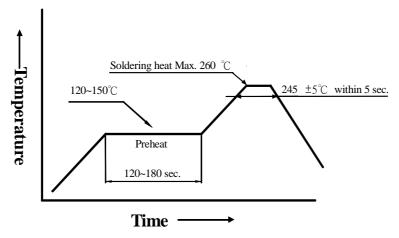


3. DIP soldering (Wave Soldering):

Preheating: 120° C ~ 150° C, within 120° 180 sec.

Operation heating : $245^{\circ}C \pm 5^{\circ}C$ within 5 sec.260°C (Max)

Gradual Cooling (Avoid quenching).



Handling:

Care must be taken not to cause to the epoxy resin portion of BRIGHT LEDs while it is exposed to high temperature.

Care must be taken not rub the epoxy resin portion of BRIGHT LEDs with hard or sharp article such as the sand blast and the metal hook.



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Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the BRIGHT LEDs within the rated figures. Also, caution should be taken not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as be subjected to reverse voltage when turning off the BRIGHT LEDs.

Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5° C 30° C (41° F)Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
- a. Completed within 168 hours.
- b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if: (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions: 48 hours at $60^{\circ}\text{C} \pm 3^{\circ}\text{C}$.

Package and Label of Products:

- (1) Package: Products are packed in one bag of 4000 pcs (one taping reel) and a label is attached on each bag.
- (2) Label:

